


KA150-2AC	Material	Thermal Impedance °C/W (Area:TO3)	Adhesive Strength N/cm	Temperature Range
Property	Aluminium Foil	0.49	5.5	-20°C to +155°C
Test Method		ASTM D5470		

Description	
	<p>Kool-Pads KA150-2AC material is designed to provide an efficient method of mounting heatsinks onto devices such as microprocessors, small electronic packages and other components, which require heatsinks.</p>
	<p>Kool-Pads KA150-2AC makes a fast and efficient thermal interface and eliminates the need for clips, clamps or any other form of mechanical fixing. The use of messy thermal compound is also eliminated. Kool-Pads KA150-2AC incorporates a highly conductive aluminium foil which is coated both sides with thermally-conductive high-strength adhesive.</p>

Ordering Information	Key Performance Properties
Standard sheet sizes are 300mm x 300mm each. KA150-2AC-30x30 An extensive range of pre-cut profiles is also available, see additional datasheet for details.	High strength bonding means no further fixing clip is required to secure component and heatsink together.
	Provided with back and front polypropylene interliner.
	Remains resistant to cleaning agents, and does not support organic growth.
	Adhesive strength increases 4 fold over initial 48 hours. No known deterioration over time.
	Easily cut at room temperature into most configurations using steel rule dies or sharp blades.
	Low tooling costs for custom profiles.

Technical Information	Property	Test Standard
Thickness (mm)	0.16 ±0.02	
Interliner	Polypropylene	
Thermal resistance per cm ²	2.90°C/W	
Hardness	90 ±5	Shore Micro
Tear Resistance kN/m	48	ASTM D624
Tensile Strength MPa	22	ASTM D412
Dielectric Constant 1000Hz	2.6	ASTM D150
Elongation %	8	ASTM D412
Colour	Cream	